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LEDs**
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FMC CONN
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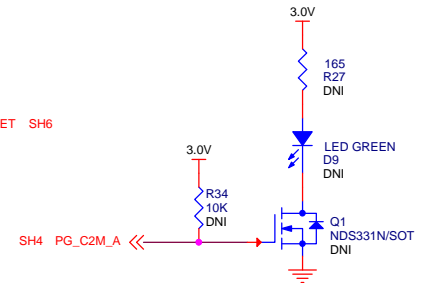
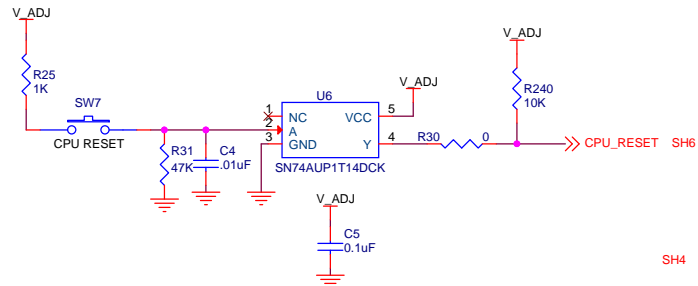
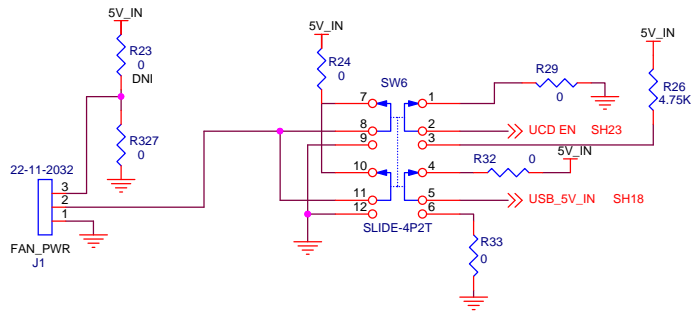
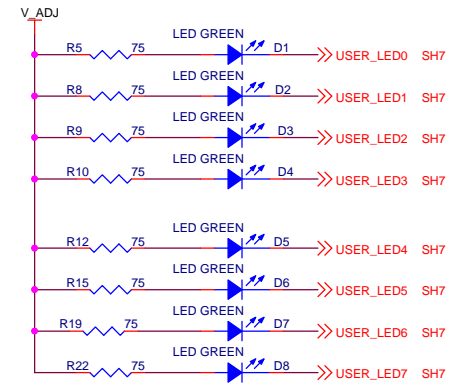
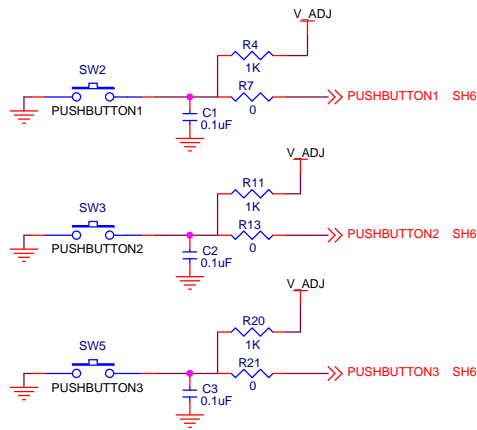
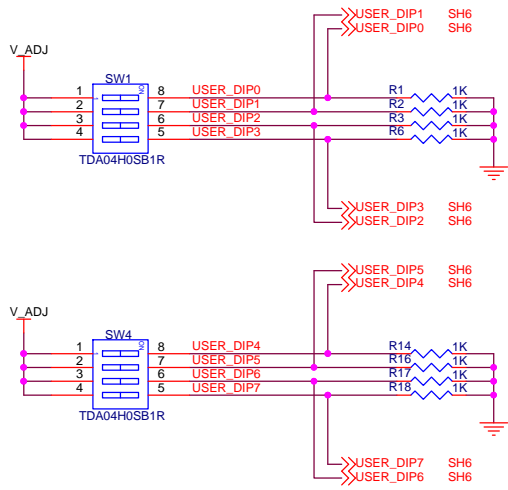
NOTE: DNI = DO NOT INSTALL COMPONENT.

 **TEXAS INSTRUMENTS**

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Drawn: L. NGUYEN	Size: B	Document Number	Rev: B
Engineer: J. SETON / E. DWOBENC	Date: Friday, August 16, 2013	Sheet 1 of 23	

Buttons, Switches, LEDs

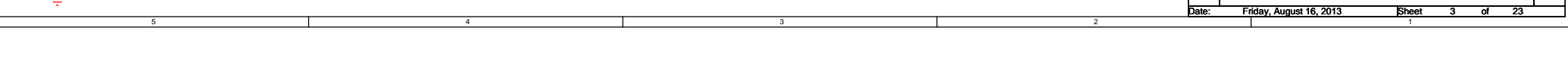
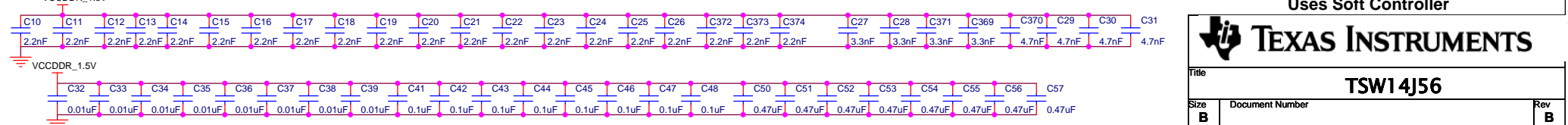
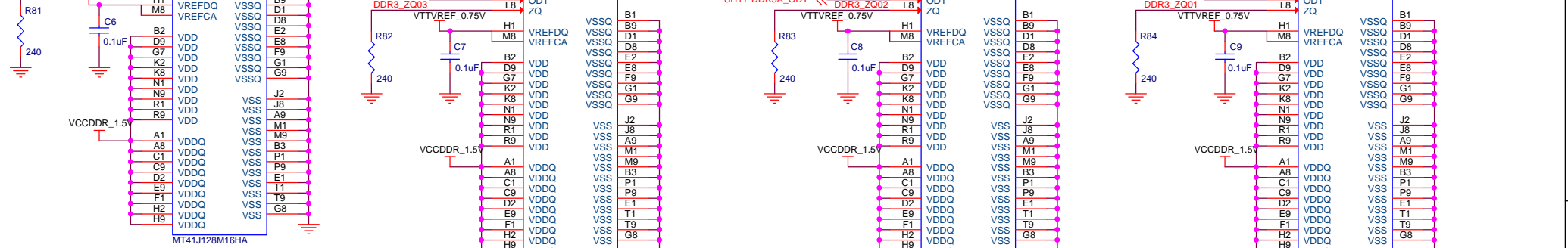
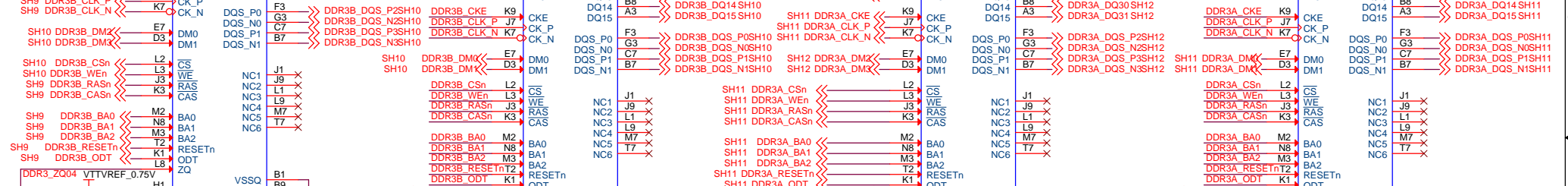
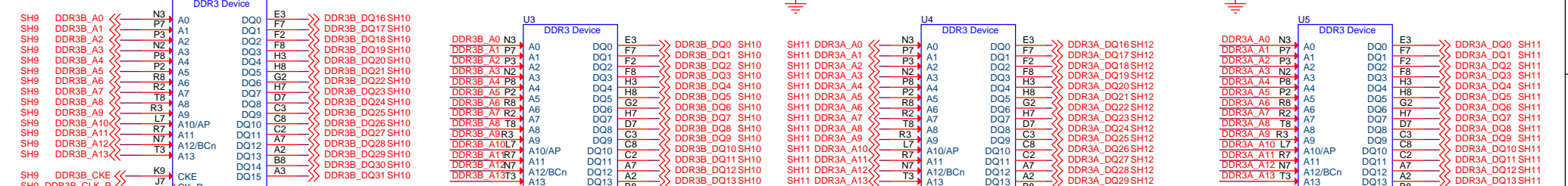
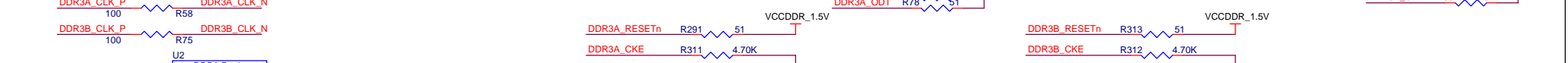
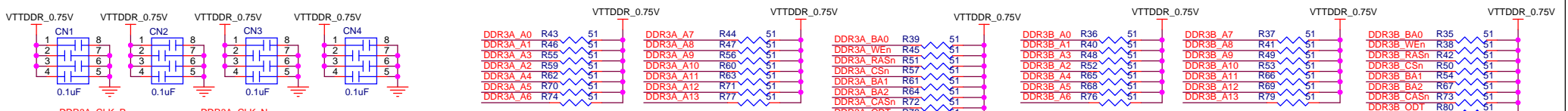


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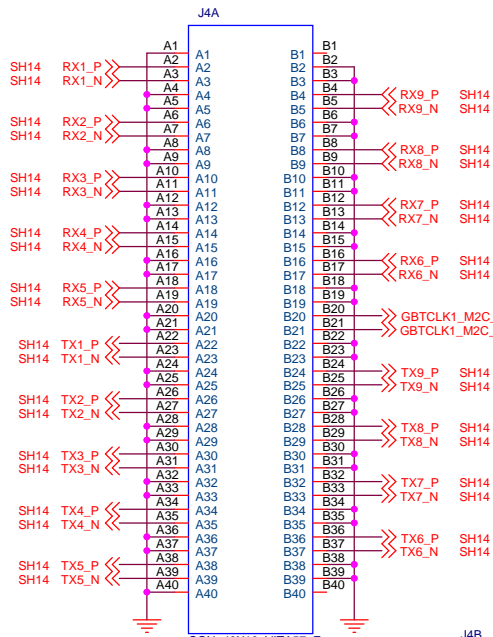
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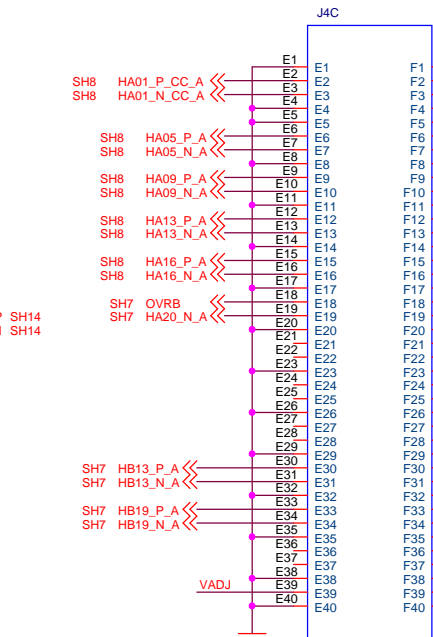
DDR III
Uses Soft Controller



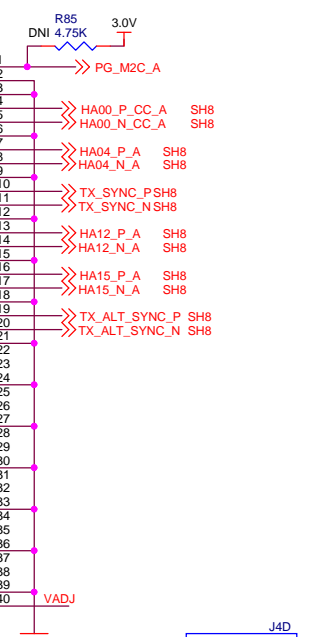
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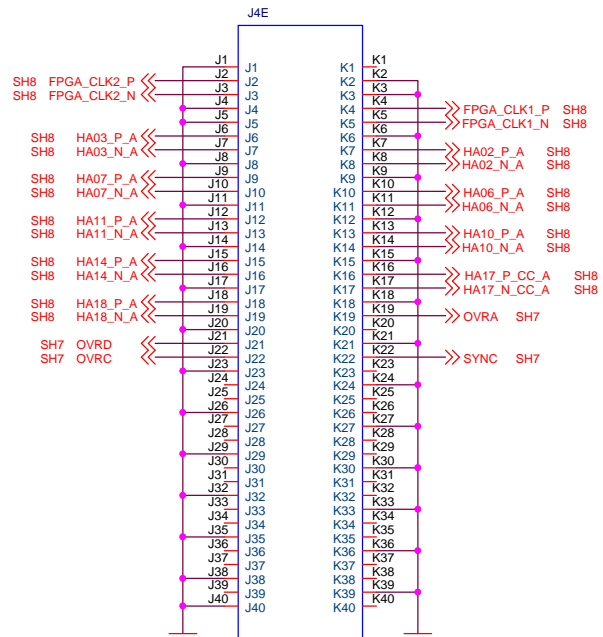
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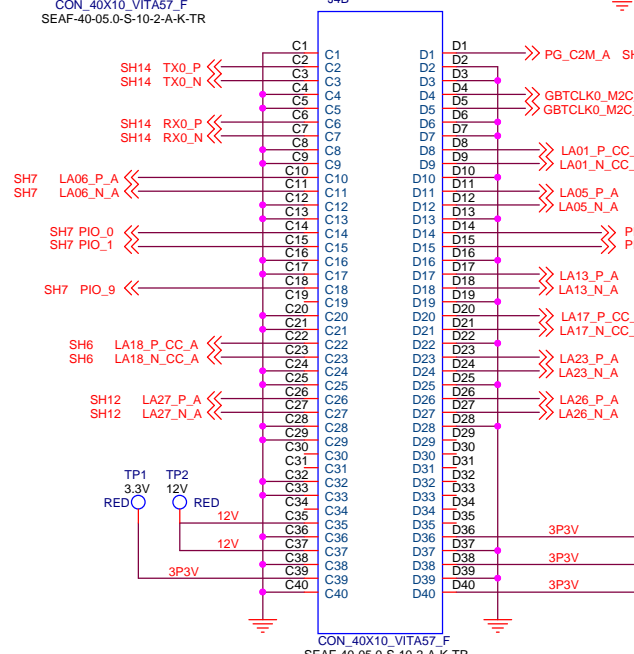
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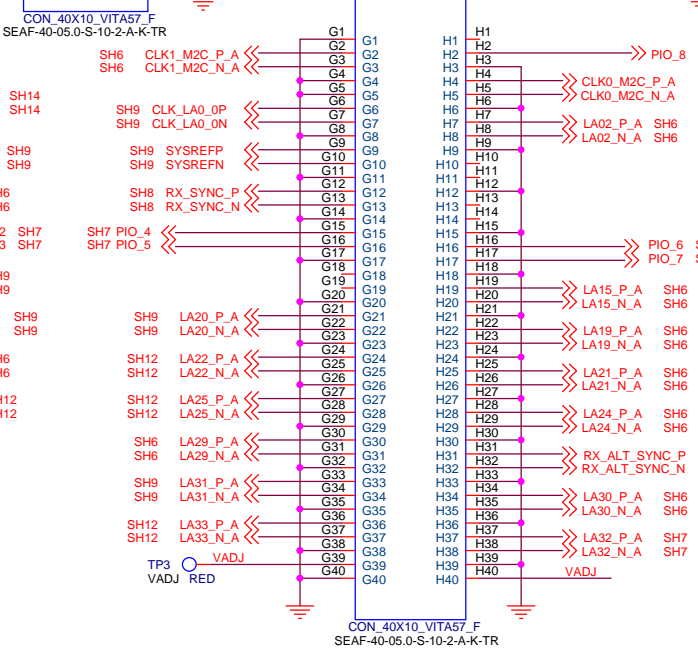
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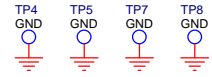
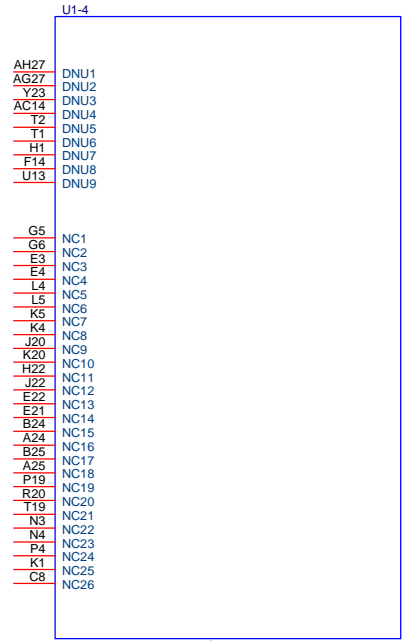
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FPGA=CARRIER
DUT=MEZ
M2C - ADC
C2M - DAC

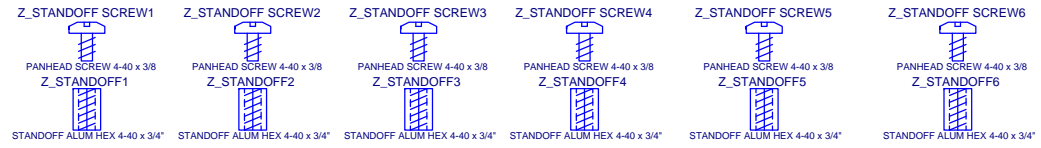
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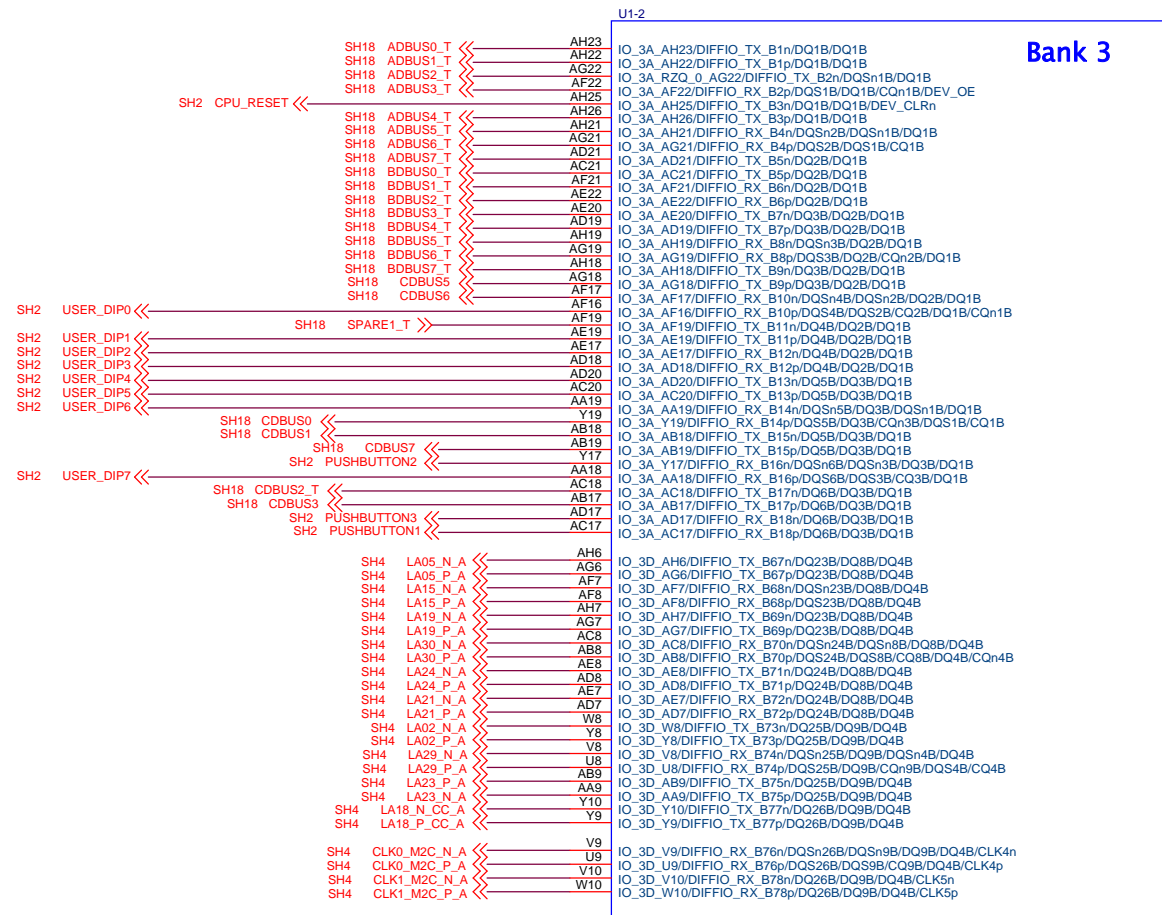
MECHANICAL PARTS



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BANK 3

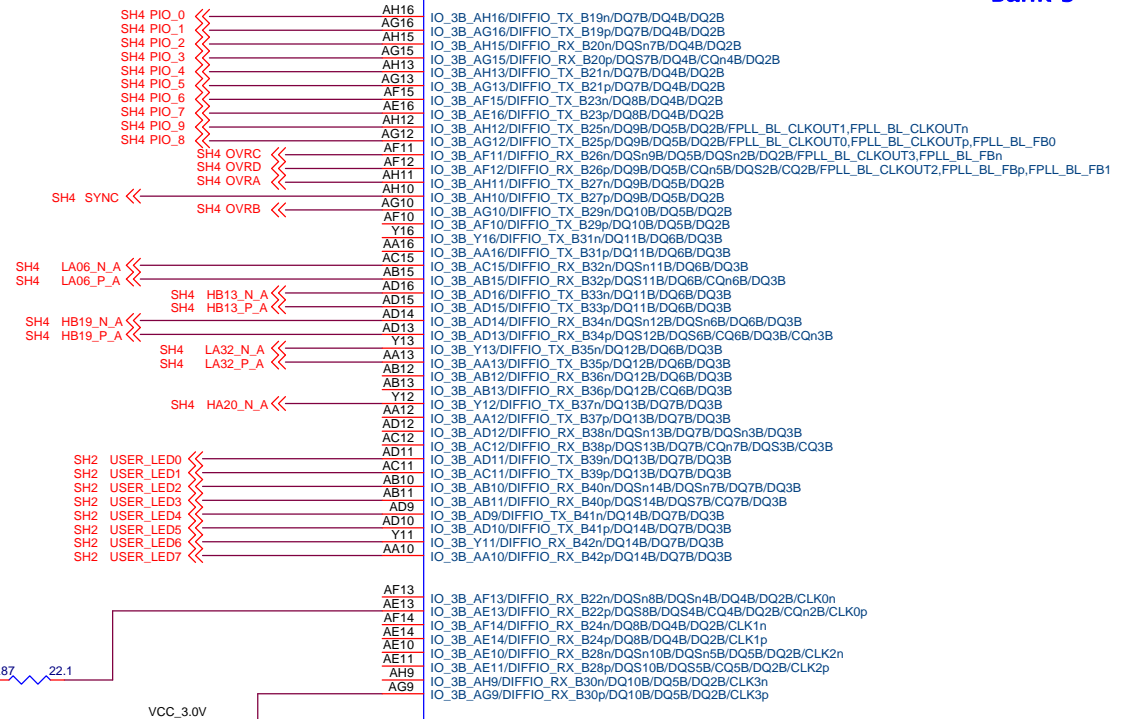


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U1-3

Bank 3

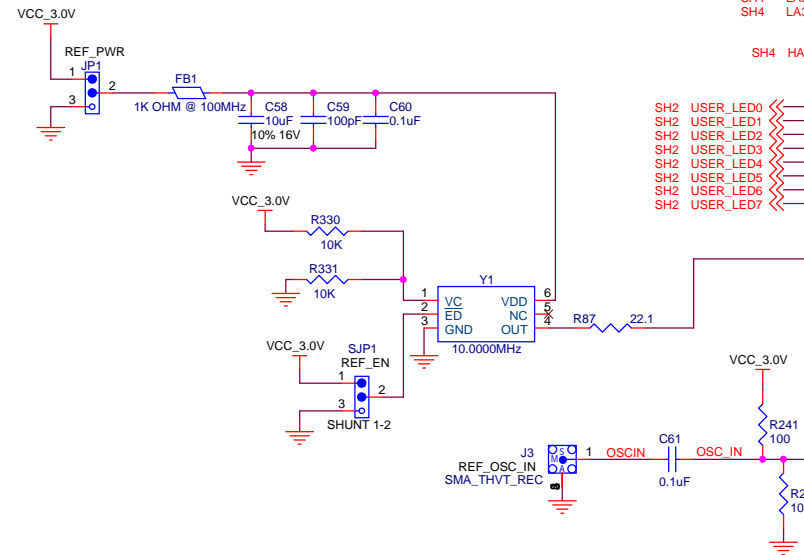


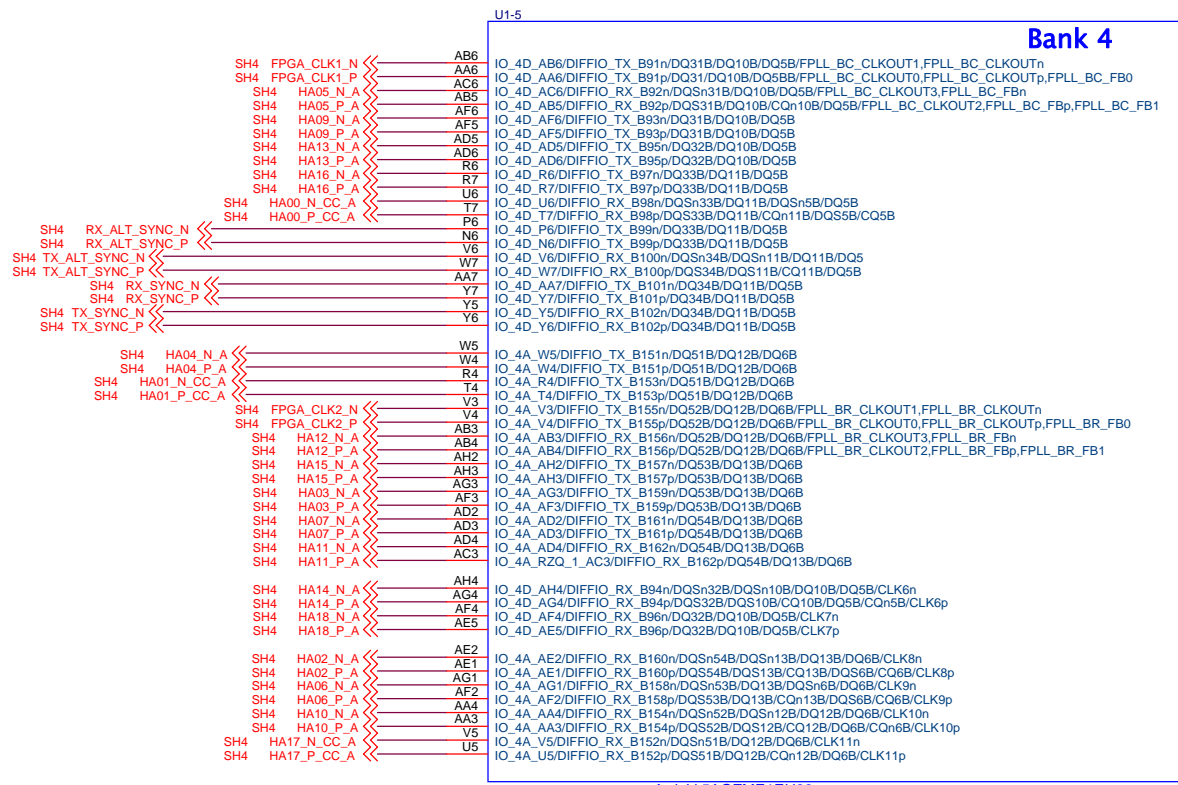
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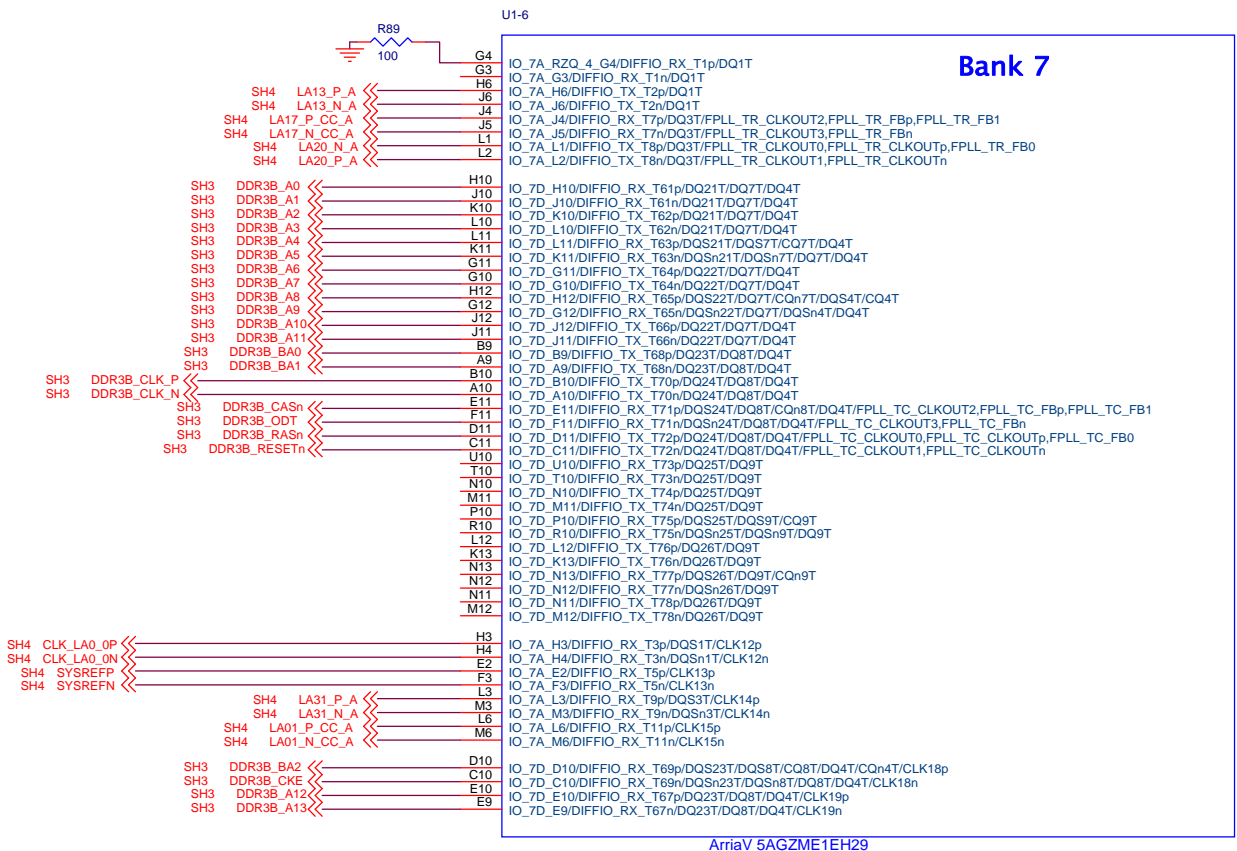


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FPGA Bank 4

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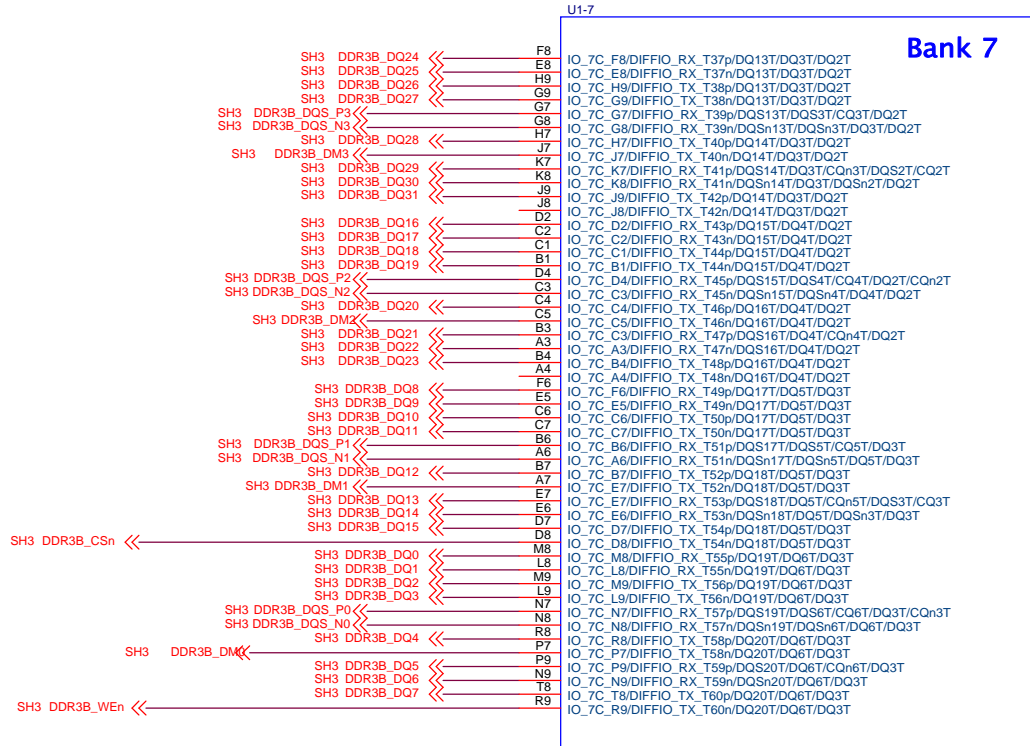
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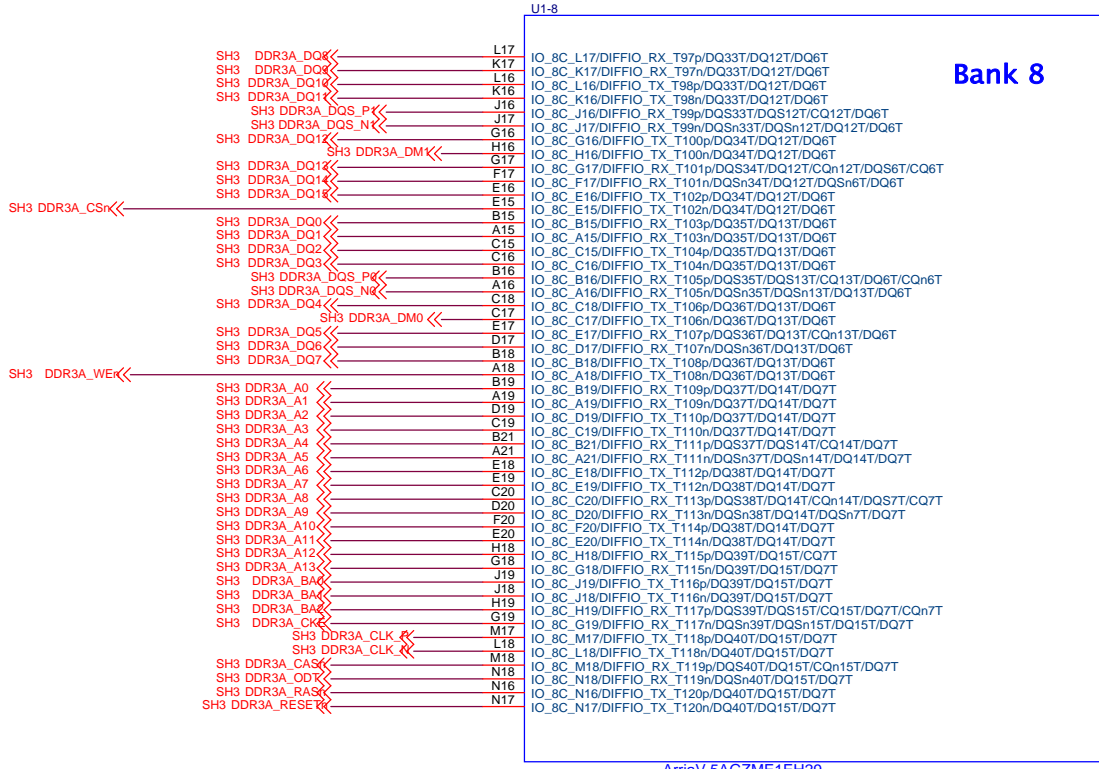
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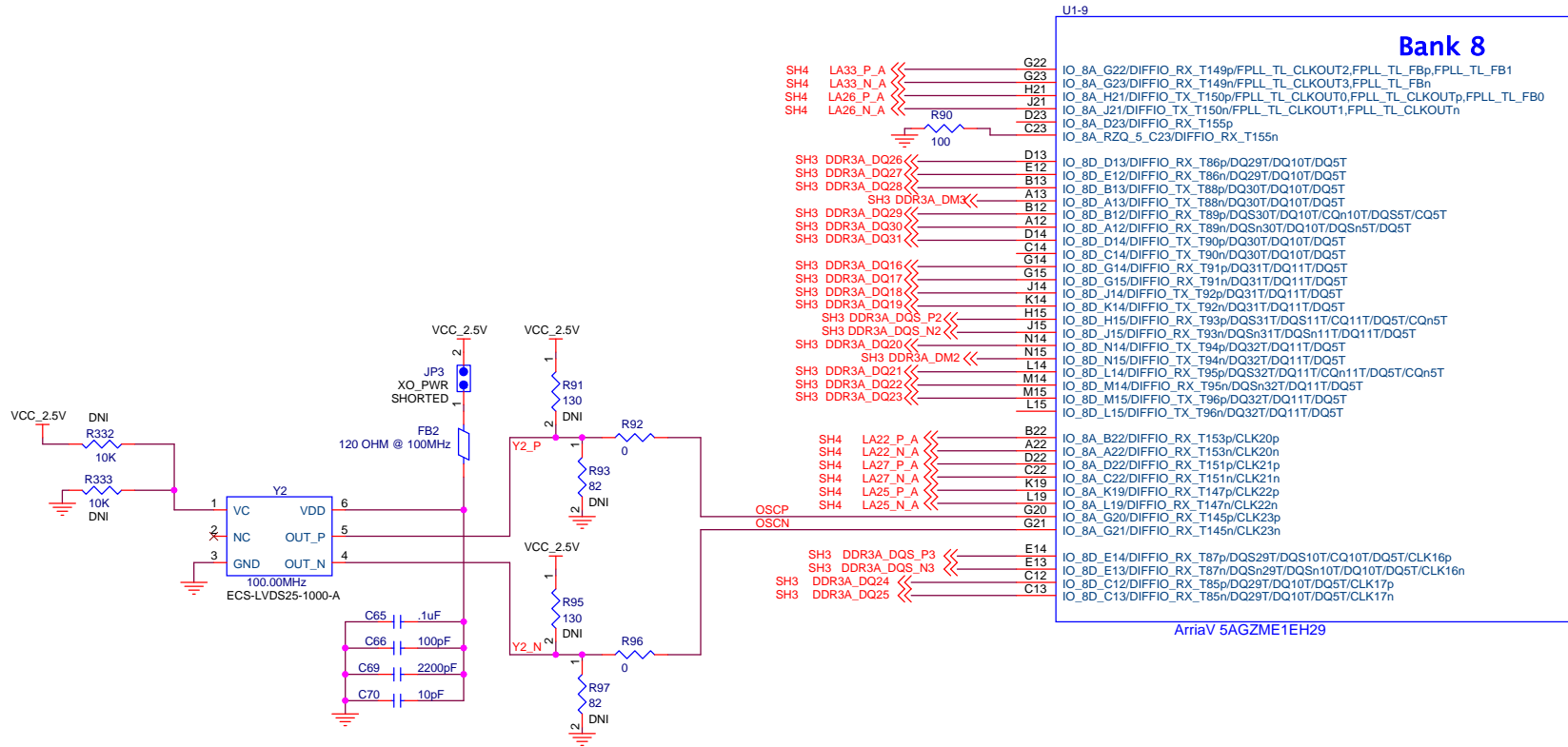


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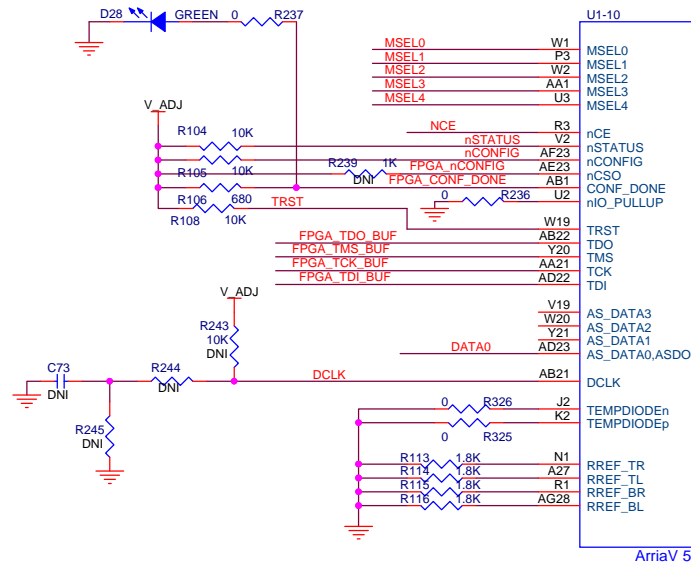
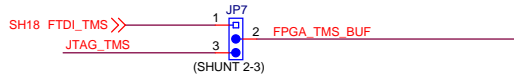
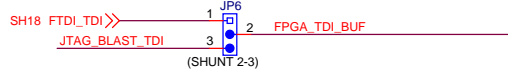
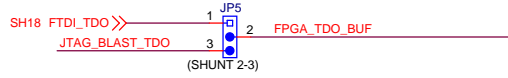
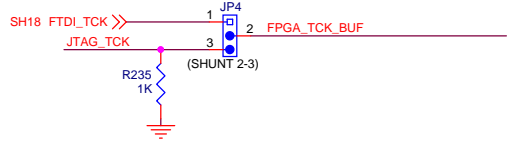
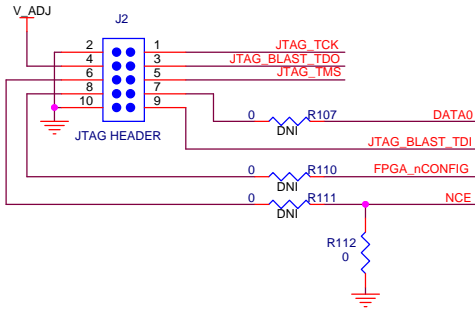
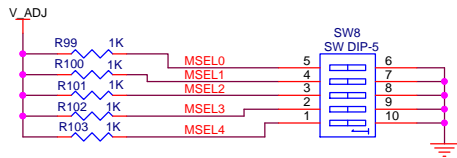
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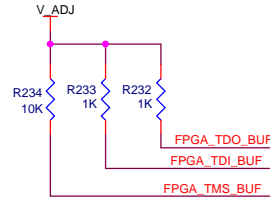
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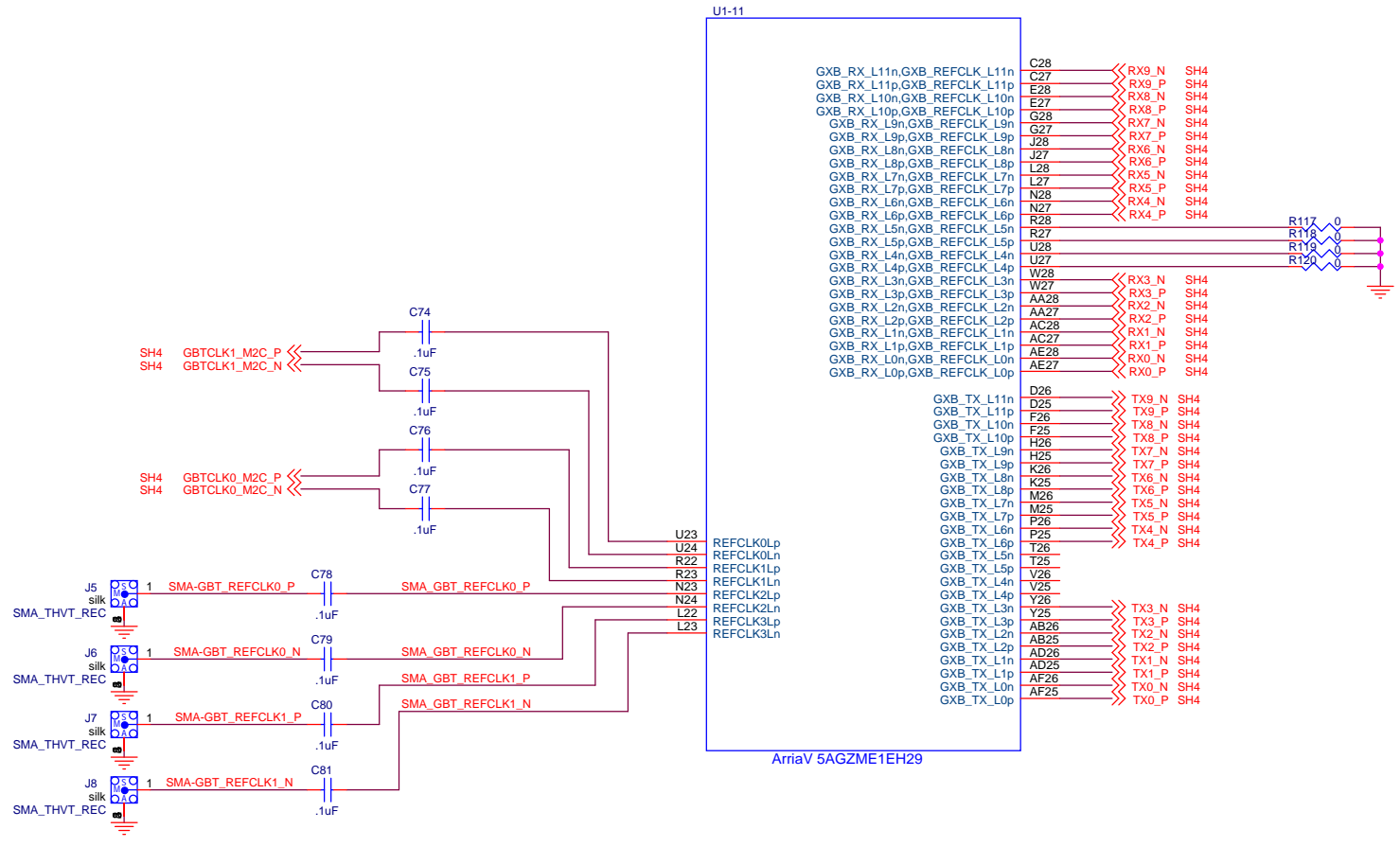


FPGA CONFIGURATION



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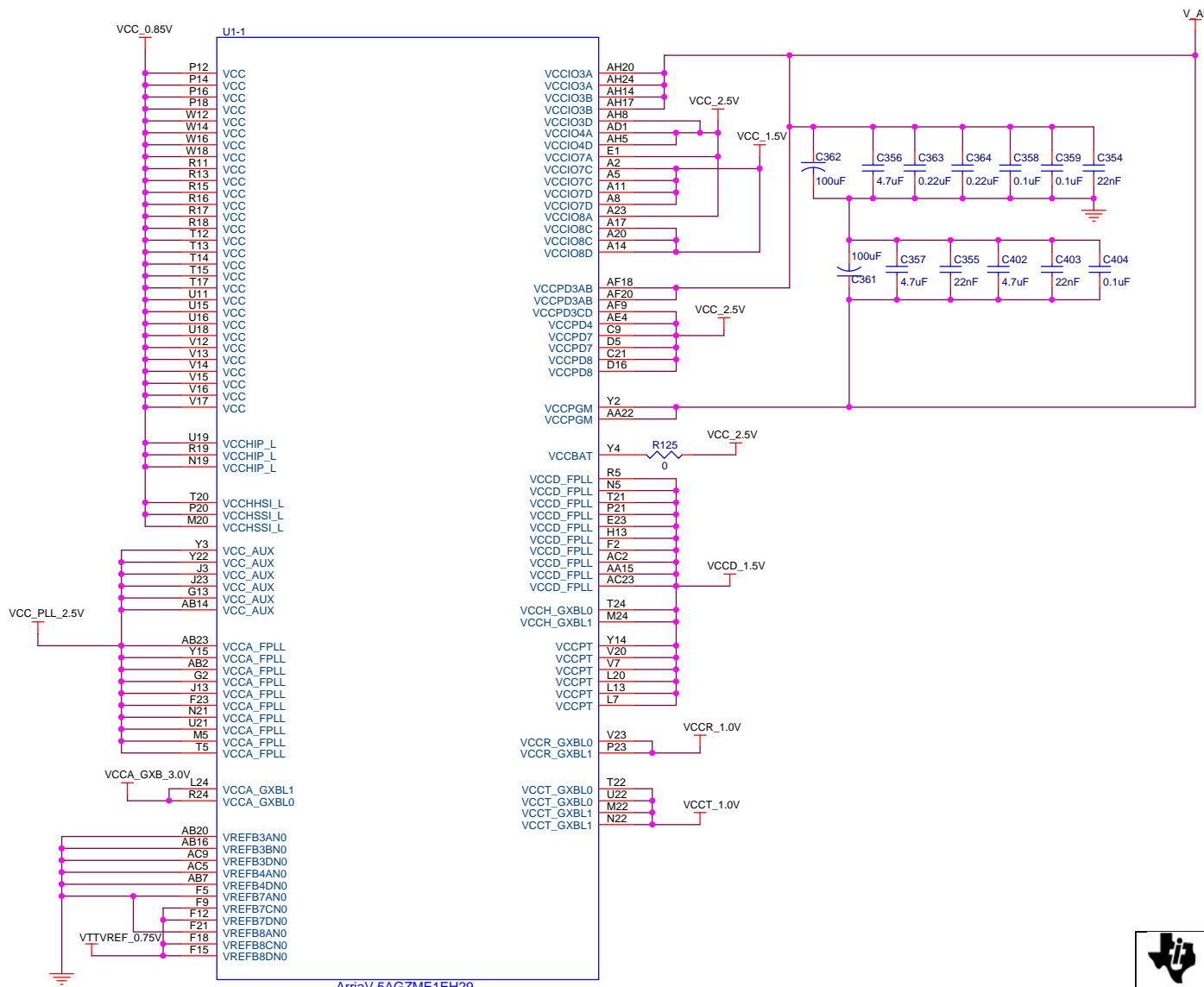
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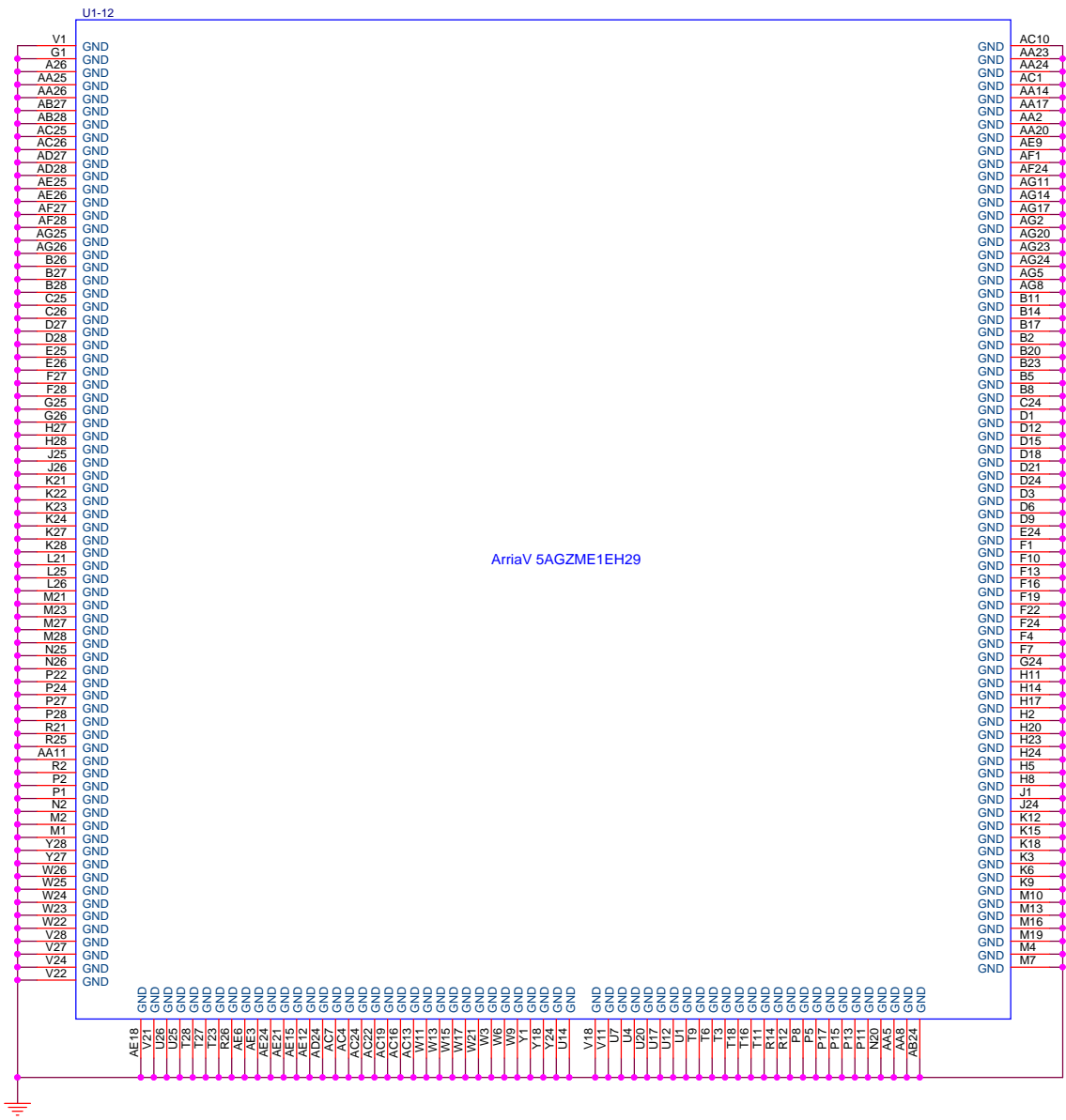


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FPGA POWER




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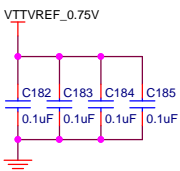
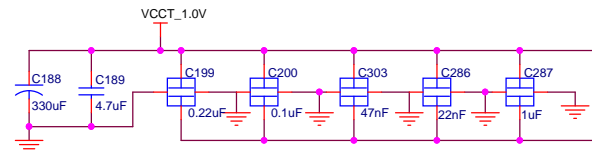
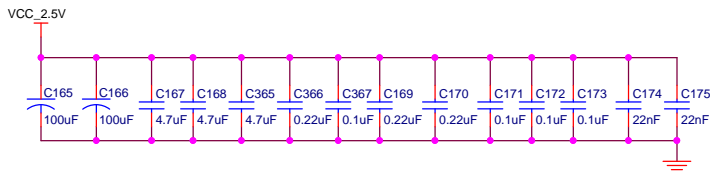
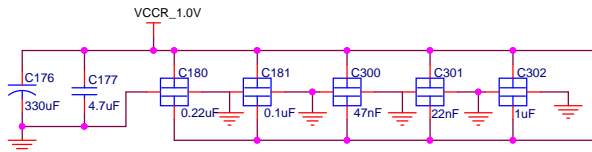
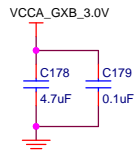
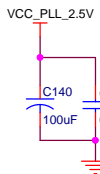
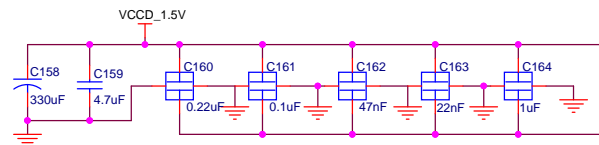
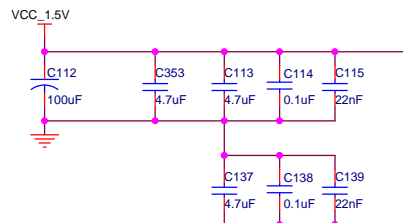
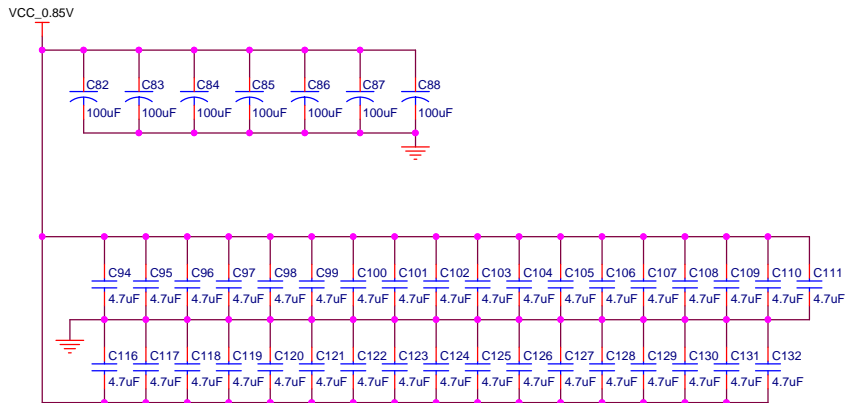
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FPGA GROUND



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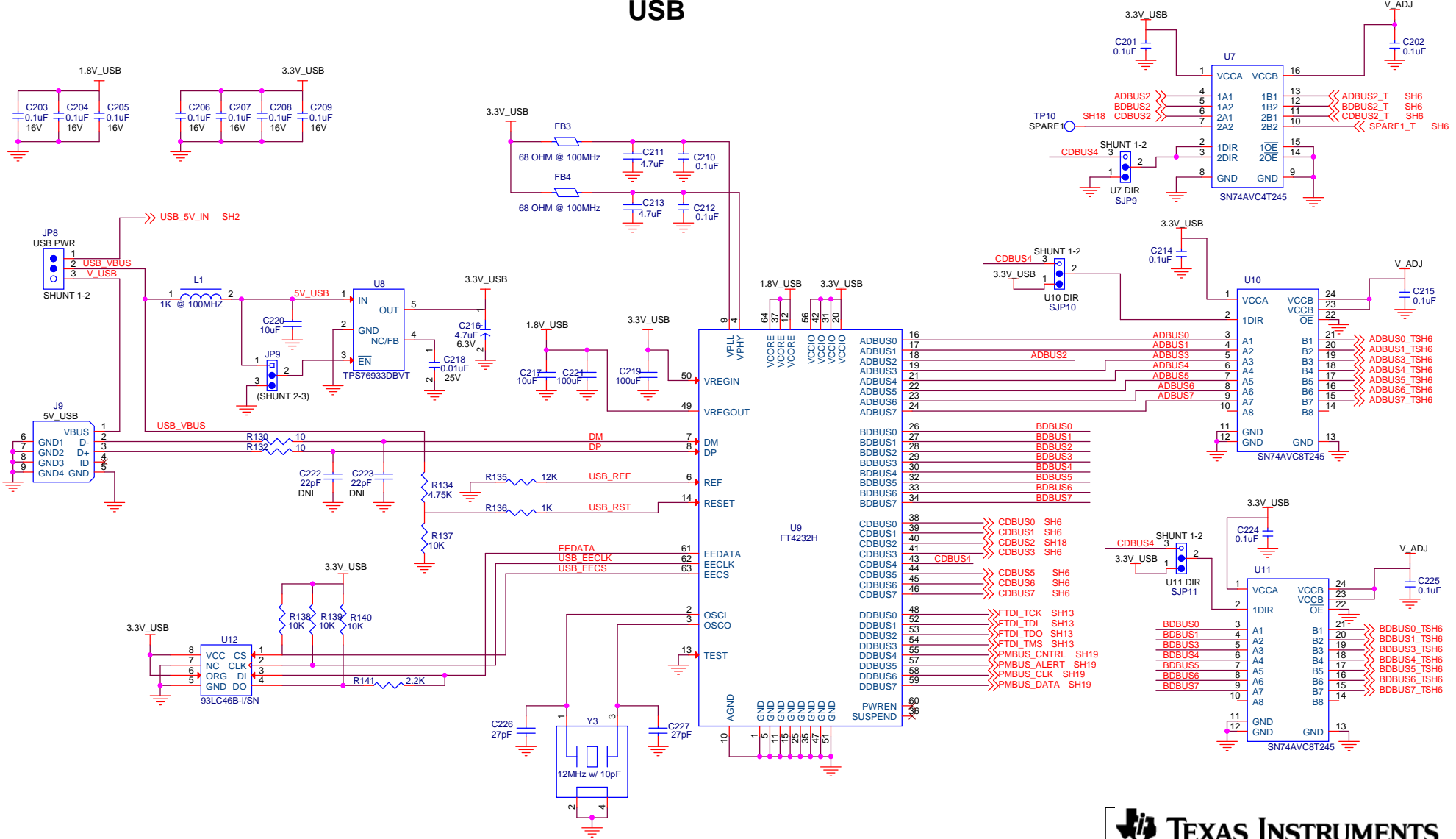


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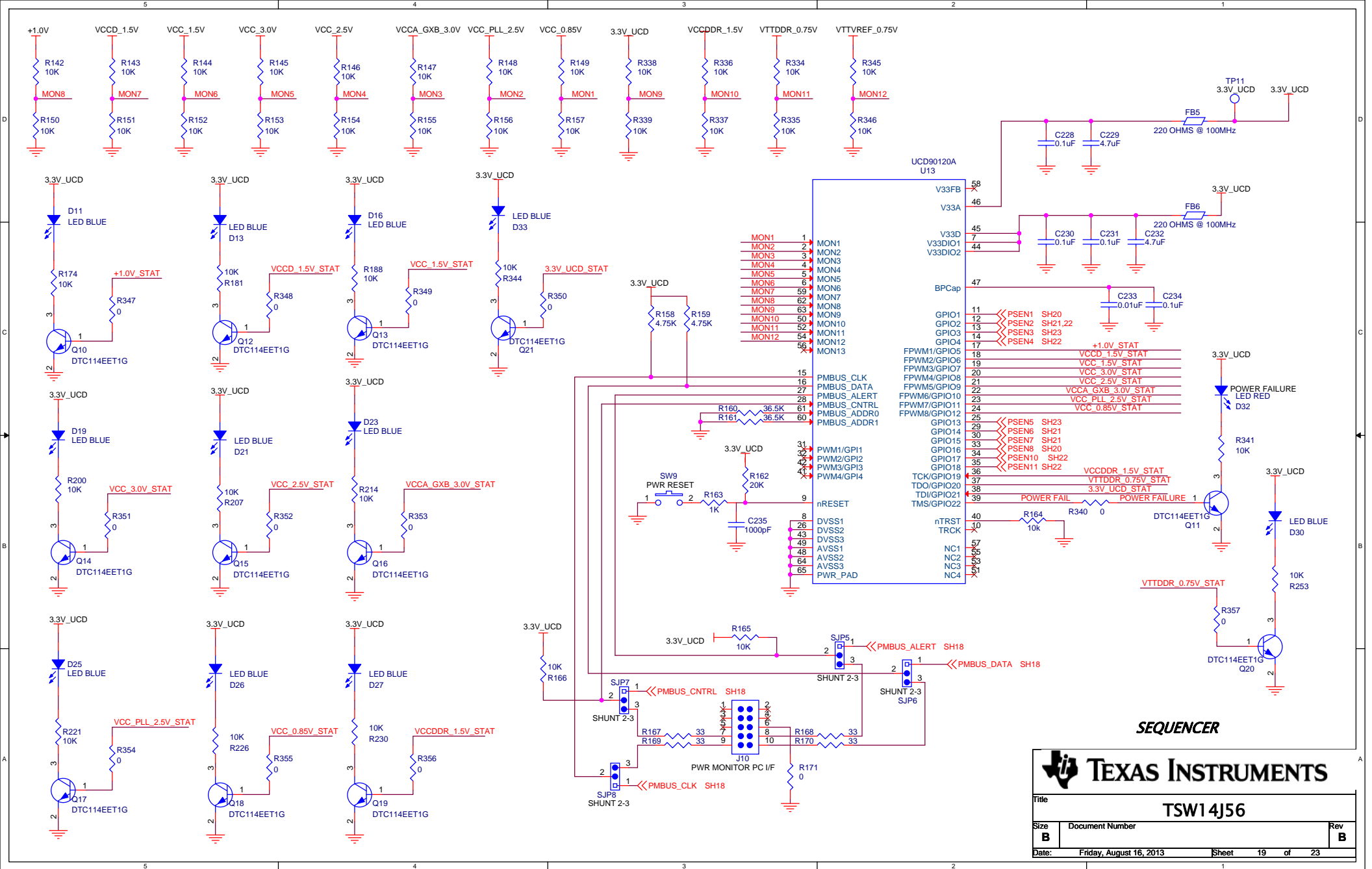
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USB



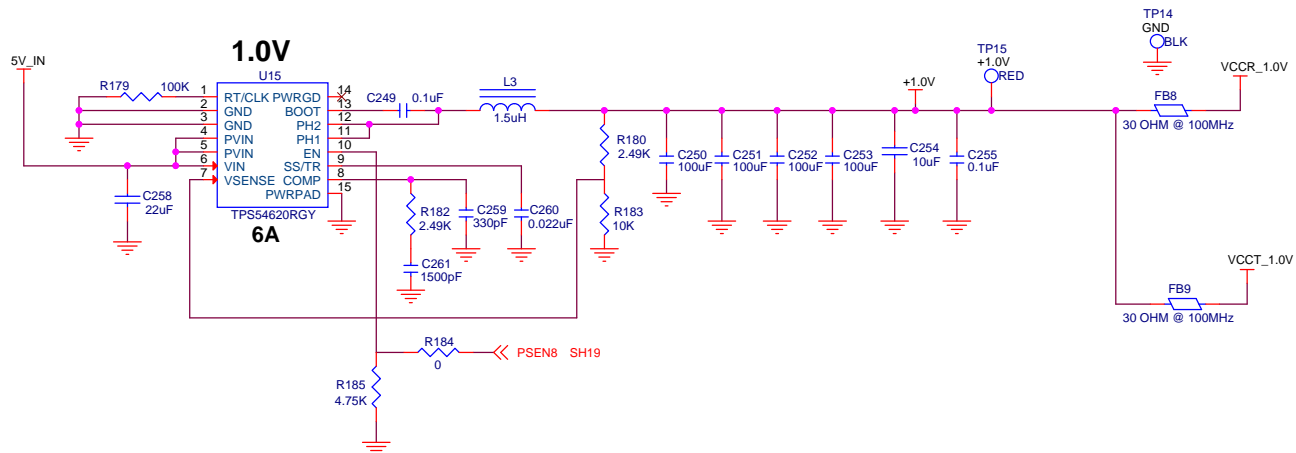
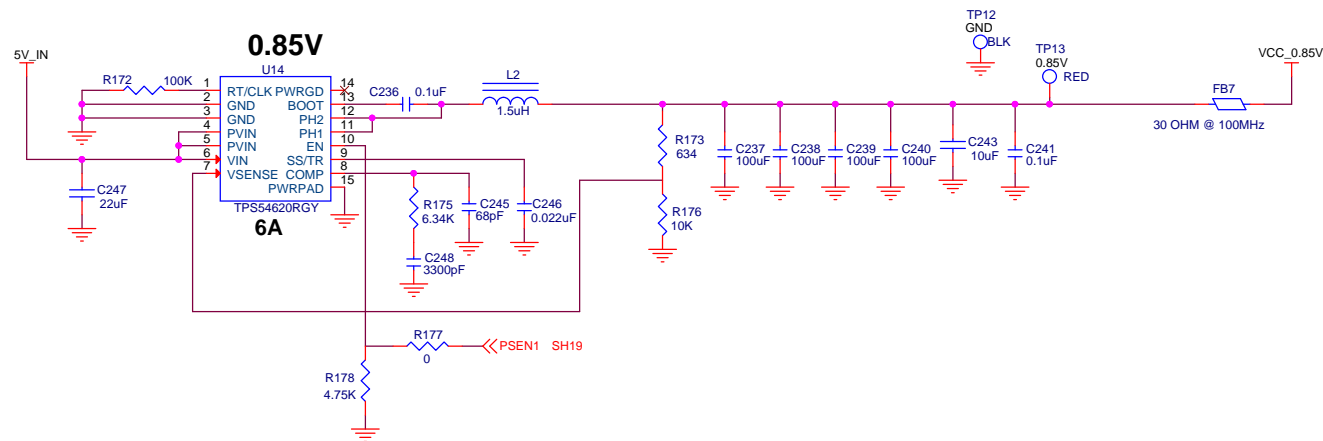
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SEQUENCER

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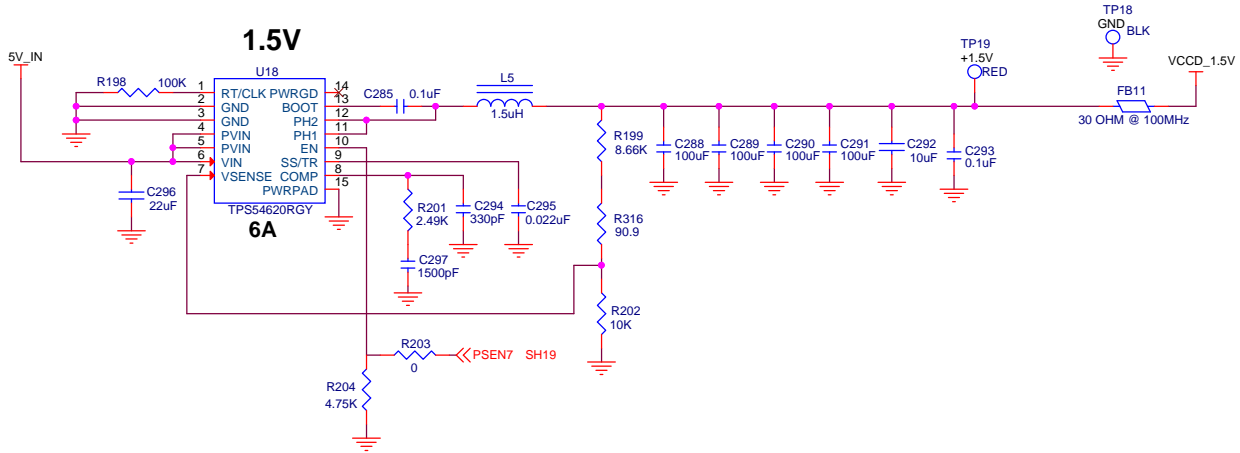
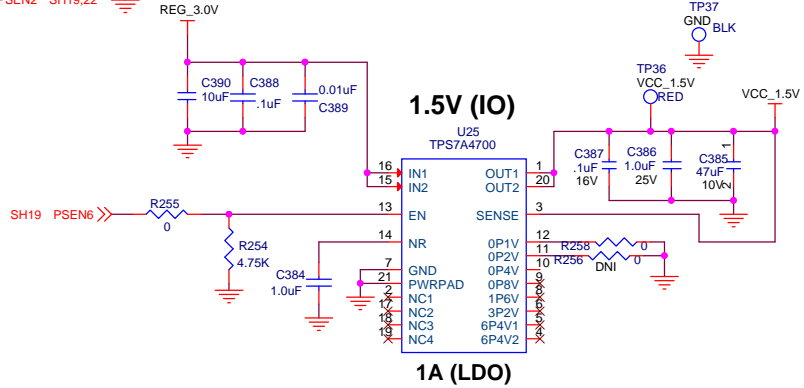
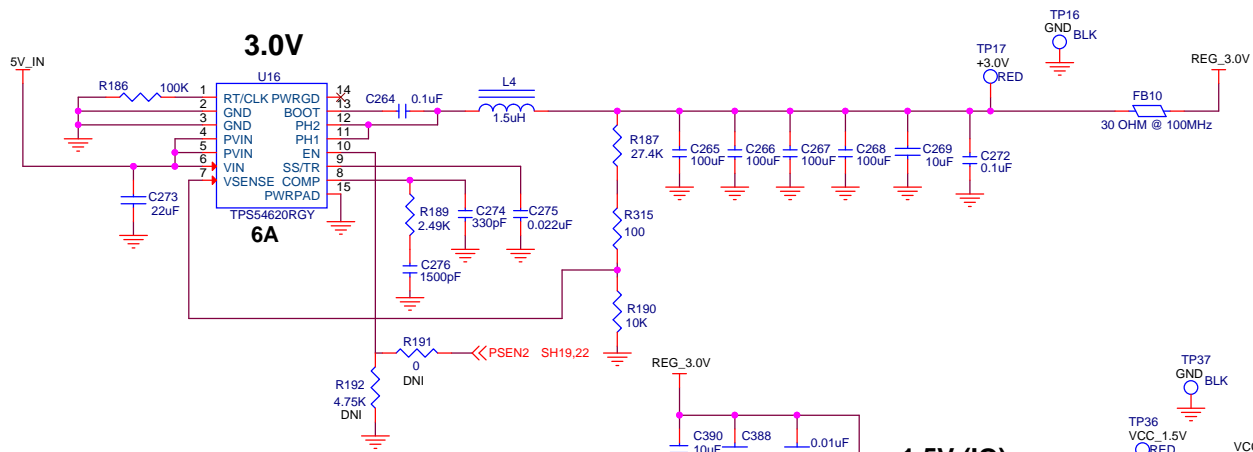
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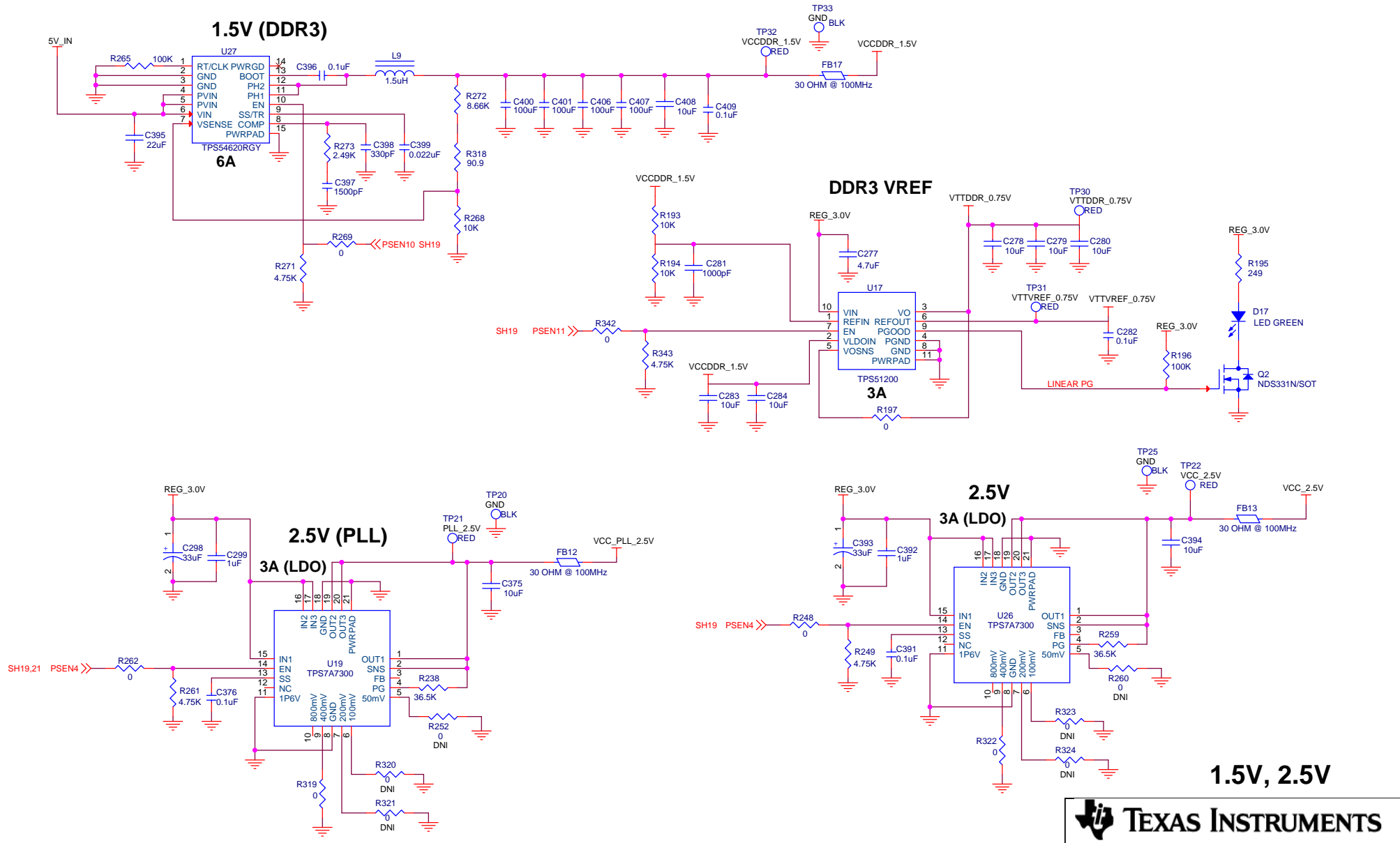
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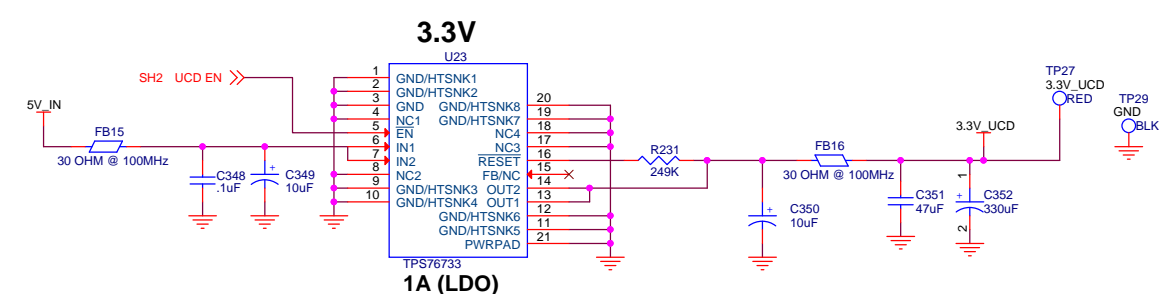
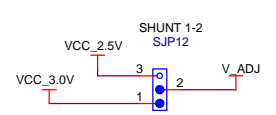
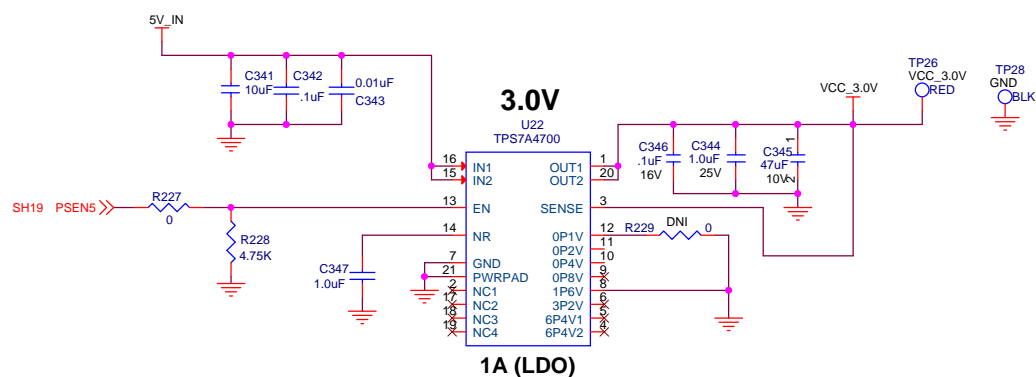
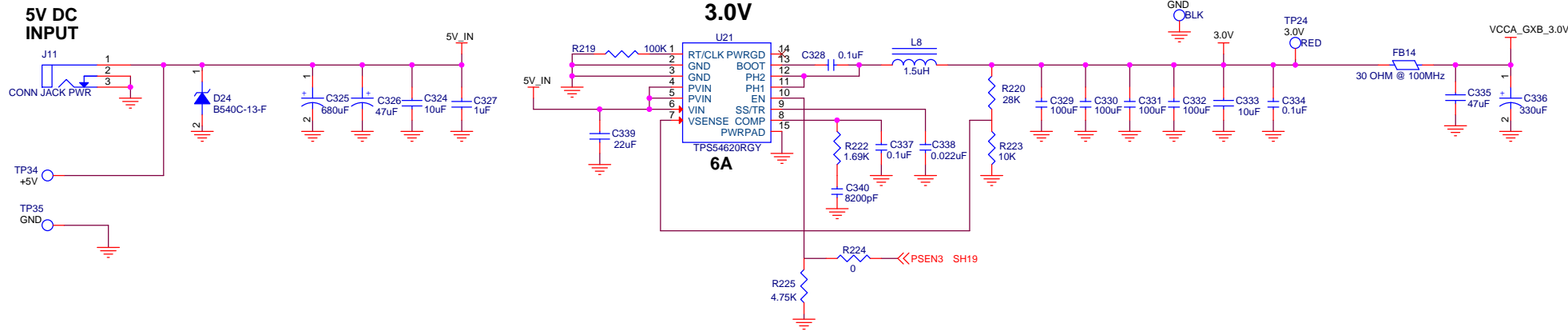
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1.5V, 2.5V



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3.0V, 3.3V

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Only those TI components that TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components that have **not** been so designated is solely at Buyer's risk, and Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.